



*Industrial Computing Platform Partner*

# ARC-615M

1U Rack Mounting Chassis

## Environment Test Report

Report NO: 07I020012

Issued by:

**Rex Chang**

/

**10/16/2007**

Test Engineer

Date

Reviewed by:

**Wenyuan Yang**

/

**10/16/2007**

Manager

Date

# Test item list

1. <i>Test item list</i> -----	2
2. <i>Temperature cycle operation test</i> -----	3
3. <i>High temperature storage test</i> -----	6
4. <i>Low temperature storage test</i> -----	8
5. <i>Humidity test</i> -----	9
6. <i>Cold start and hot start test</i> -----	10

Num	Item	Spec
1.	1U Chassis:	<b>ARC-615M</b>
2.	Main Board	AAEON FWB-880 A1.0
	1. BIOS	FWB-880/FWS-825 BIOS Rev 1.1
	2. CPU	Intel Pentium 4 / 3.4GHz /LGA775
	3. Chipset	Intel 945G + Intel 82801FB (ICH7R)
	4. VGA	Integrated VGA on Intel 945G
	5. Memory	512MB / DDR2 667 / ELPIDA E5108AG-6E-E * 2
3.	<b>HDD</b>	Seagate ST380815AS / 80GB Seagate ST3160811AS / 160GB
4.	Power Supply	Zippy P1H-6400P ATX Power

# Temperature cycle test

**Test Date:** 10-12~14-2007

**Test Product:** ARC-615M

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC68-2-14 Testing procedures  
Test Nb: Change of temperature Test

**Test Equipment:**

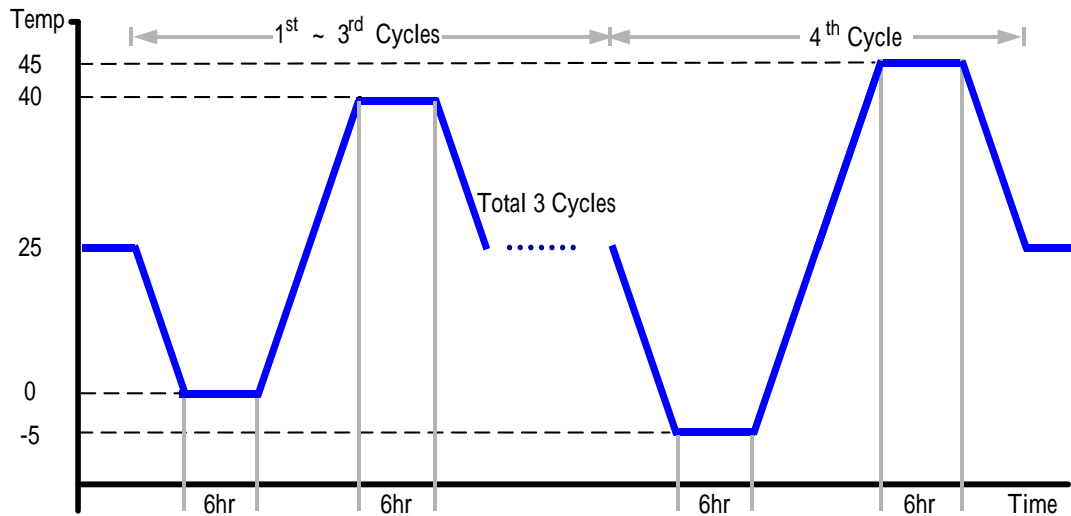
Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.  
Model: THS-D4H+-100  
Date of Calibration: 05/16/07  
Serial Number: 1241

**Temperature Measurement:**

40 Channel Thermal Recorder:  
YOKOGAWA Inc,  
Model: DA100-13-1D  
Date of Calibration: 12/11/06  
Serial Number: 12A323190

**Test Condition:**

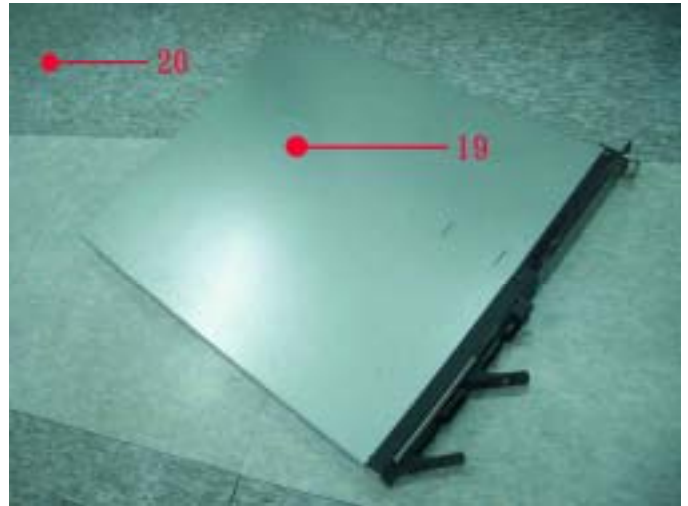
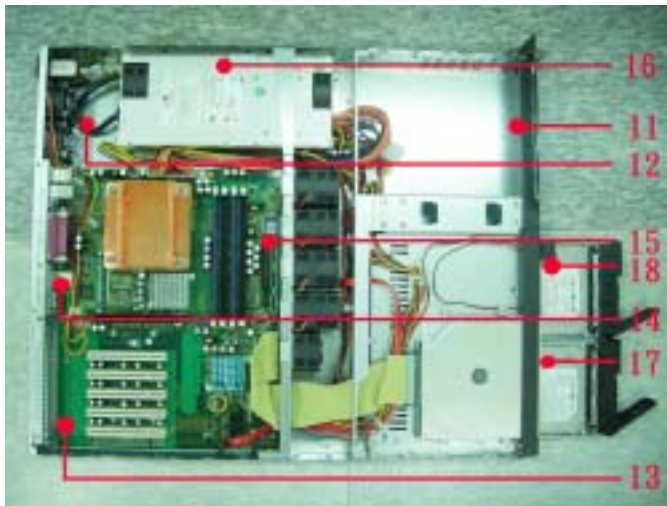
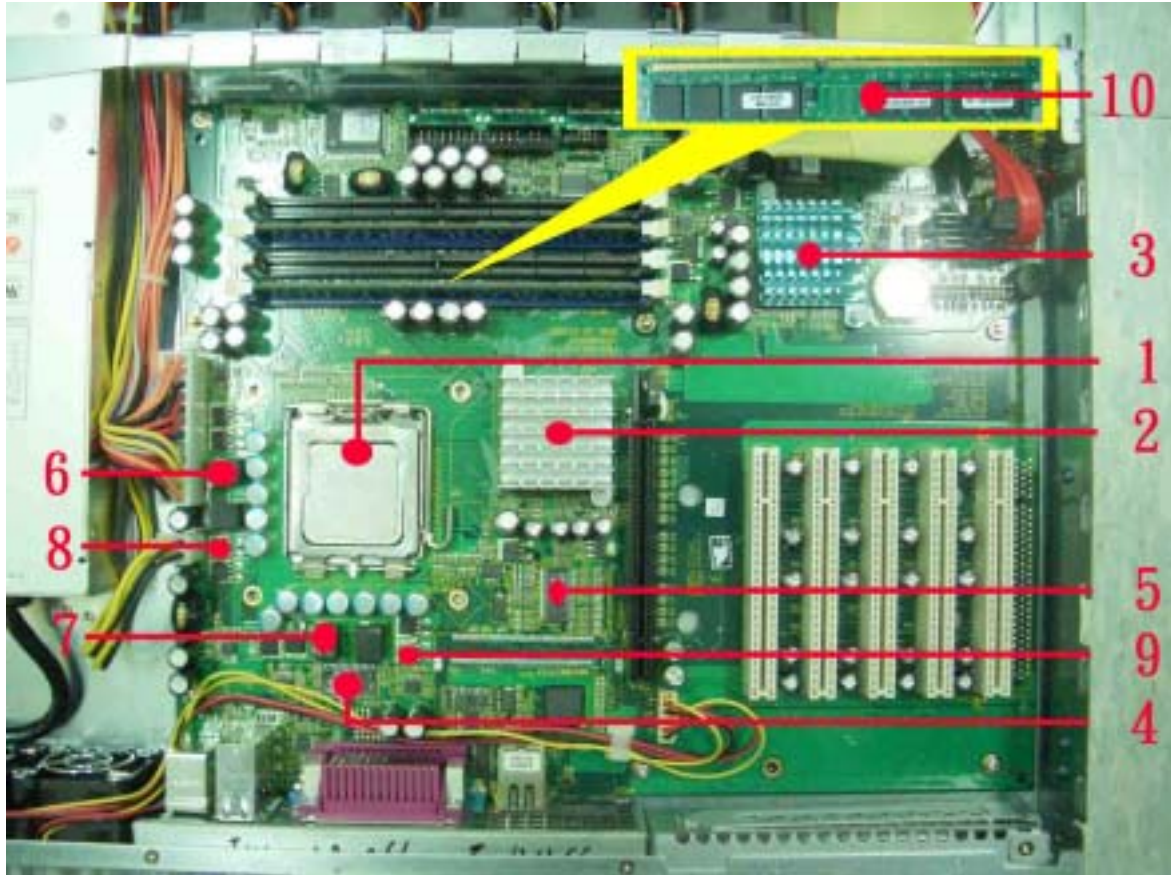
1. Test Low Temperature: 0 (1~3 cycles)  
-5 (4<sup>th</sup> cycle)
2. Test High Temperature: 40 (1~3 cycles)  
45 (4<sup>th</sup> cycle)
3. Test dwell time: 6Hrs
4. Temperature slope: 2 /min
5. Test cycle: 4 cycles
6. Test Environment Curve:



# Temperature cycle test

## Temperature Recorder:

Measuring Thermal Couple Position :



# Temperature cycle test

## Thermal profile data:

### ARC-615M

Point	Temp. Stage( )	Spec	40	25	0
1. Intel Pentium 4 3.4GHz / LGA775 CPU		67	66.8	51.8	26.8
2. U18- (TF) IC.SMD.Chipset LAKEPORT 945G.INTEL.QG82945G SL8FU A2		99	60.7	45.7	20.7
3. U22 - (TF) IC.SMD.Chipset ICH7R.INTEL.NH82801GR SL8FY A1		100	54.3	39.3	14.3
4. U15 - (TF)IC.SMD.SOIC 28Pin PWM Controller.Intersil.ISL6556BCBZ		70	57.1	42.1	17.1
5. U17 - (TF)IC.SMD.SSOP56.Clock Generator.ICS. ICS954101DFLF		115	59.9	44.9	19.9
6. L14 - (TF)COIL.0.56uH.20%.DIP.Wire Size.GMAS120911P-0R56M		85	68.3	53.3	28.3
7. L6 - (TF)COIL.0.56uH.20%.DIP.Wire Size.GMAS120911P-0R56M		85	69.7	54.7	29.7
8. Q9 - (TF)PWR.SMD.TO-252.N-Channel PowerMosfet.ON SEMI.NTD78N03T4G		150	65.3	50.3	25.3
9. Q3 - (TF)PWR.SMD.TO-252.N-Channel PowerMosfet.ON SEMI.NTD78N03T4G		150	61.0	46.0	21.0
10. Memory		70	49.5	34.5	9.5
11. Control box inside air temperature - 1		N/A	42.3	27.3	2.3
12. Control box inside air temperature - 2		N/A	48.8	33.8	8.8
13. Control box inside air temperature - 3		N/A	45.3	30.3	5.3
14. Control box inside air temperature - 4		N/A	46.4	31.4	6.4
15. Control box inside air temperature - 5		N/A	43.7	28.7	3.7
16. Power supply external surface		50	49.7	34.7	9.7
17. HDD - 1		55	43.0	28.0	3.0
18. HDD - 2		55	42.8	27.8	2.8
19. Control box external surface		N/A	43.3	28.3	3.3
20. Chamber Air Temperature		N/A	40.9	25.9	0.9
<b>1. Any Tm value showed in red words which meaning the value over the Tc + 5 degree C of this device specification.</b>					

## Sample Configuration & Quantity Under Test:

Quantity: 1 (ARC-615M)

## Test Result:

No problem was found during the temperature cycle operation test.

# High temperature storage test

**Test Date:** 10-12~14-2007

**Test Product:** ARC-615M Chassis

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-2 Testing procedures  
Test Bb: Dry Heat Test (Non-operation)

**Test Equipment:**

Programmable Temperature & Humidity Chamber

K.SON. INS. TECH. CORP.

Model: THS-D7S-100+1 N2

Date of Calibration: 12/11/06

Serial Number: 3898

**Testing Item:**

1. Test Temperature: 80
2. Test Times: 48Hrs
3. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (ARC-615M Chassis)

**Test Result:**

No problem was found after the high temperature storage test.

# High temperature storage test

**Test Date:** 10-14~16-2007

**Test Product:** ARC-615M

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-2 Testing procedures  
Test Bb: Dry Heat Test (Non-operation)

**Test Equipment:**

Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.  
Model: THS-D7S-100+1 N2  
Date of Calibration: 12/11/06  
Serial Number: 3898

**Testing Item:**

4. Test Temperature: 60
5. Test Times: 48Hrs
6. Test Software: Windows XP / Run PassMark Burn In Test Pro 4.0
7. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (ARC-615M)

**Test Result:**

No problem was found after the high temperature storage test.

# Low temperature storage test

**Test Date:** 10-07~09-2007

**Test Product:** ARC-615M

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-1  
Testing procedures Test Ab: Cold Test (Non-operation)

**Test Equipment:**

Programmable Temperature & Humidity Chamber

K.SON. INS. TECH. CORP.

Model: THS-D7S-100+1 N2

Date of Calibration: 12/11/06

Serial Number: 3898

**Testing Item:**

1. Test Temperature: -20
2. Test Times: 48Hrs
3. Test Software: Windows XP / Run PassMark Burn In Test Pro 4.0
4. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (ARC-615M)

**Test Result:**

No problem was found after the low temperature storage test.



# Humidity test

**Test Date:** 10-09~11-2007

**Test Product:** ARC-615M

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-3 Testing procedures  
Test Ca: Damp heat, steady state (Non-operation)

**Test Equipment:**

Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.

Model: THS-D7S-100+1 N2

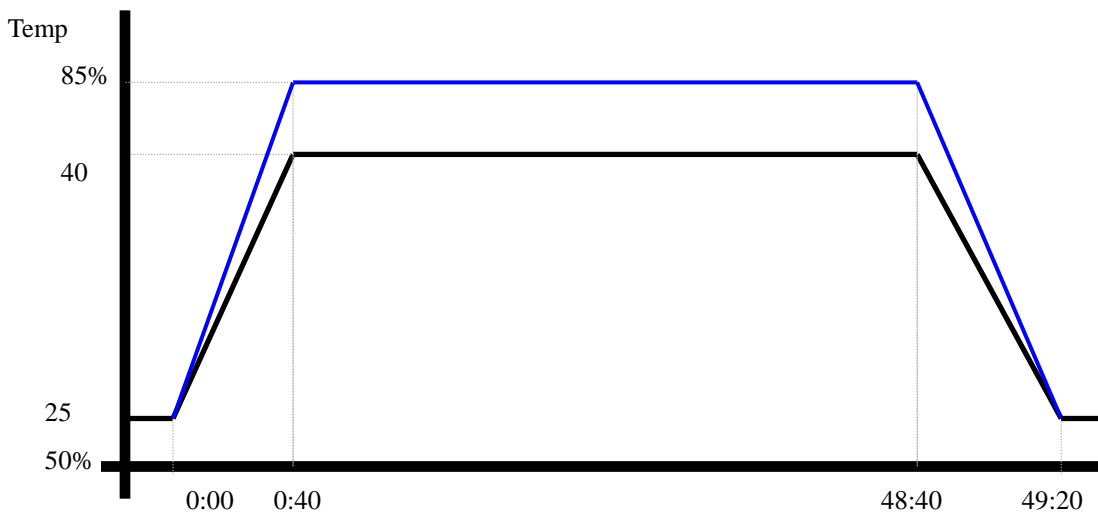
Date of Calibration: 12/11/06

Serial Number: 3898

**Testing Item:**

1. Test Temperature: 40
2. Test Humidity: 85%RH
3. Test Times: 48Hrs
4. Test Software: Windows XP / Run PassMark Burn In Test Pro 4.0
5. Test Environment Curve:

**Humidity %**



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (ARC-615M)

**Test Result:**

No problem was found after the humidity test.

# Cold start and hot start test

**Test Date:** 10-15~16-2007

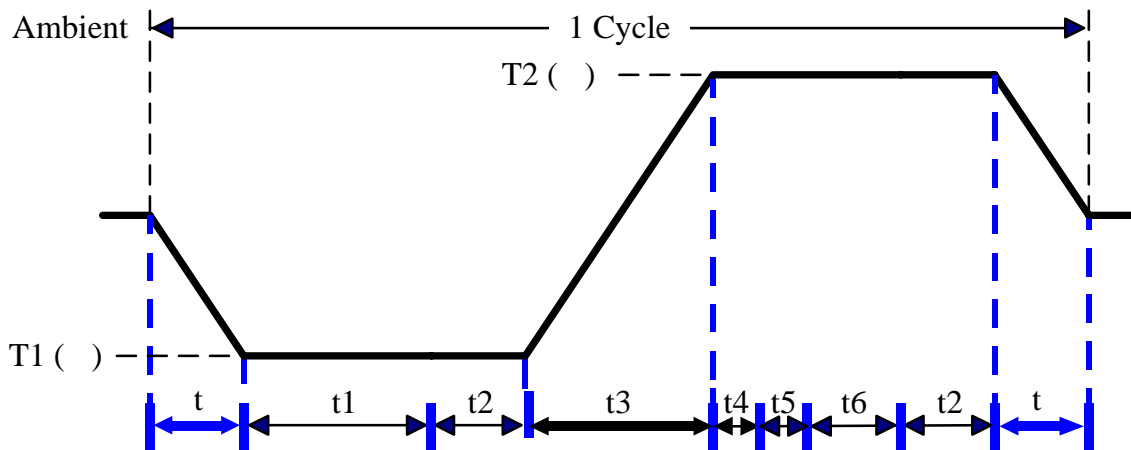
**Test Product:** ARC-615M

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-14 Testing procedures  
Test Nb: Change of temperature Test

**Test Equipment:**  
Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.  
Model: THS-D4H+-100  
Date of Calibration: 05/16/07  
Serial Number: 1241

**Test Condition:**



Parameters	Description
T1	-5
T2	45
t1	4 hrs
t2, t6	2 hrs
t4, t5	1hrs
t, t3	2 /min
n (Cycle)	1

t = temperature slope  
t, t1, t6: Power Off  
t2: Power on/off test 10 times (on 2 min / off 5min)  
t3, t4: Run PassMark Burn In Test  
t5: Win XP Software restart test 3 times  
Test Software: Windows XP

**Test Result:**

- a. No problem was found during the cold start test.
- b. No problem was found during the hot start test.